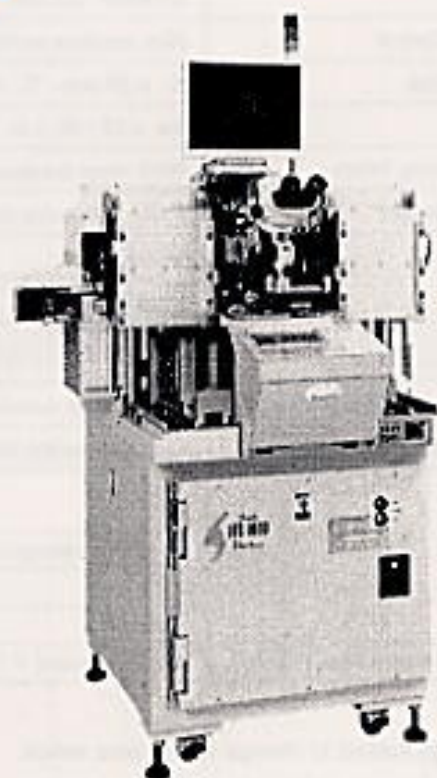


EQUIPMENT

UTC-1000 *Super*



Shimkama

Capability to Handle Stacked CSPs and SiPs

Wire Bonder Designed for Leading Edge Packages

- With Shinkawa RPS technology, world's first closed loop control of capillary tip position provides solution to misplaced bonding of fine pitch devices and feasibility to perform 40 μ m pad pitch bonding.
- Shinkawa NRS technology minimizes vibration which is a great obstacle for fine pitch bonding, and sustains permanent bondability.
- Variety of optimum loop modes for bonding of stacked dies incorporated as a standard capability.
- Numerous automated features save workload of operators.

Specifications

ITEM	DETAILS	
Bonding Accuracy	$\pm 2.5 \mu\text{m}$ (at 3σ) Using Shinkawa standard device	
Bonding Placement Assurance	Placement offset system compensates prior to bonding through Shinkawa RPS	
Bonding Speed	67ms/2 mm wire with loop control (Varies depending on device conditions)	
Bonding Wire Length	8 mm maximum (Varies depending on device conditions)	
Resolution	XY-table: $0.1 \mu\text{m}$ Z-axis: $0.1 \mu\text{m}$	
Vibration Control	Non reaction servo system through Shinkawa NRS	
Bonding Area	X: $\pm 28 \text{ mm}$ Y: $\pm 33 \text{ mm}$	
Wire Size	Au $\phi 15 - 38 \mu\text{m}$ diameter	
No. of Bonding Wires	8000 wires maximum	
Loader/Unloader	Fully automatic magazine stacker system	
Work Size	Width	20 - 80 mm (20 - 78 mm when carrier type)
	Length	95 - 262 mm
	Thickness	0.07 - 2.0 mm (Varies depending on work family) (Conversion parts are required when thickness change)
Production Management	Availability management through production management monitor, etc.	
Options Available	Communication interface SECS I/SECS II, HSMS, GEM	
Utilities	Electricity	100VAC (other voltages require transformer) 50/60Hz ($\pm 5\%$ input variation)
	Power Consumption	Approx. 1000W
	CDA	500 kPa (5 kgf/cm ²) 60 l/min.
	Vacuum	Below -74 kPa (-550 mmHg) (gage)
Physical Dimensions and Mass	700W(Cabinet) $\times$ 700D(Cabinet) $\times$ 1940H mm Approx. 500 kg	

Specifications subject to change without prior notice.

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